

# Product Change Notification - LIAL-22YHTT084

#### Date:

01 Aug 2018

**Product Category:** 

8-bit Microcontrollers

#### Affected CPNs:

#### 7

# Notification subject:

CCB 3227 and 3227.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L SOIC package at GTK assembly site.

## Notification text:

PCN Status:

Final notification.

PCN Type:

Manufacturing Change

# **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

# **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L SOIC package at GTK assembly site. **Pre Change:** 

Using gold (Au) bond wire, CRM-1076DJ die attach and G600 mold compound material **Post Change:** 

Using palladium coated copper with gold flash (CuPdAu) bond wire, 4900GC die attach and G700 mold compound material.

## Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Greatek Electronic	Greatek Electronic				
	Inc.(GTK)	Inc.(GTK)				
Wire material	Au	CuPdAu				
Die attach material	CRM-1076DJ	4900GC				
Molding compound material	G600	G700				
Lead frame material	A194	A194				

## Impacts to Data Sheet:

None

Change Impact:

None

## **Reason for Change:**

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

# **Change Implementation Status:**

In Progress

# **Estimated First Ship Date:**

September 01, 2018 (date code: 1836)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

## Time Table Summary:

	February 2018			>	August 2018				September 2018							
Workweek	05	06	07	08	09		31	32	33	34	35	36	37	38	39	40
Initial PCN Issue Date	Х															
Qual Report Availability							Х									
Final PCN Issue Date							Х									
Estimated Implementation Date												Х				

#### Method to Identify Change:

Traceability code

#### Qualification Report:

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

## **Revision History:**

February 01, 2018: Issued initial notification

February 19, 2018: Revised the PCN to update the affected part list

**August 01, 2018:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date on September 01, 2018.

#### Attachment(s):

PCN\_LIAL-22YHTT084\_Qual\_Report.pdf

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Affected Catalog Part Numbers (CPN)

PIC12F675-C/SN PIC12F675-E/SN PIC12F675-I/SN PIC12F675-I/SN102 PIC12F675-I/SN112 PIC12F675-I/SN166 PIC12F675-I/SN172 PIC12F675-I/SN177 PIC12F675-I/SN202 PIC12F675-I/SNC15 PIC12F675T-C/SN PIC12F675T-E/SN PIC12F675T-E/SN073 PIC12F675T-E/SN082 PIC12F675T-E/SN091 PIC12F675T-I/SN PIC12F675T-I/SN026 PIC12F675T-I/SN049 PIC12F675T-I/SN075 PIC12F675T-I/SN079 PIC12F675T-I/SN085 PIC12F675T-I/SN121 PIC12F675T-I/SN131 PIC12F675T-I/SN145 PIC12F675T-I/SN150 PIC12F675T-I/SN152 PIC12F675T-I/SN153 PIC12F675T-I/SN166 PIC12F675T-I/SN172 PIC12F675T-I/SN173 PIC12F675T-I/SN178 PIC12F675T-I/SN179 PIC12F675T-I/SN185 PIC12F675T-I/SN190 PIC12F675T-I/SN191 PIC12F675T-I/SN194 PIC12F675T-I/SN195 PIC12F675T-I/SN199 PIC12F675T-I/SN200 PIC12F675T-I/SN201 PIC12F675T-I/SN202 PIC12F675T-I/SN206 PIC12F675T-I/SN207 PIC12F675T-I/SNC15 PIC12F683-E/SN PIC12F683-E/SN084

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PIC12F683-I/SN PIC12F683-I/SN PIC12F683-I/SN075 PIC12F683-I/SNAU PIC12F683T-E/SN PIC12F683T-E/SN040 PIC12F683T-E/SN079 PIC12F683T-E/SN084 PIC12F683T-E/SN092 PIC12F683T-E/SN097 PIC12F683T-E/SN098 PIC12F683T-I/SN PIC12F683T-I/SN061 PIC12F683T-I/SN062 PIC12F683T-I/SN072 PIC12F683T-I/SN091 PIC12F683T-I/SNAU